CLAIMS

1. A method for manufacturing an electronic device, the method comprising at least:

a preparing step of preparing a structure provided with an adhesive film provided with a base material layer, an adhesive resin layer (A) provided on a first surface side of the base material layer and used for temporarily fixing an electronic component, an adhesive resin layer (B) provided on a second surface side of the base material layer and in which an adhesive force is reduced by external stimuli, and an unevenness-absorbing resin layer (C) provided between the base material layer and the adhesive resin layer (A) or between the base material layer and the adhesive resin layer (B), an electronic component attached to the adhesive resin layer (A) of the adhesive film and having an uneven structure, and a support substrate attached to the adhesive resin layer (B) of the adhesive film; and

a sealing step of sealing the electronic component with a sealing material~~.~~,

wherein the uneven structure of the electronic component includes a bump electrode, and

wherein, when a height of the bump electrode is defined as H [μm] and a thickness of the unevenness-absorbing resin layer is defined as d [μm], H/d is 0.01 or more and 1 or less.

2. The method for manufacturing an electronic device according to claim 1,

wherein the unevenness-absorbing resin layer (C) is provided at least between the base material layer and the adhesive resin layer (A).

~~3. The method for manufacturing an electronic device according to claim 1 or 2,~~

~~wherein the uneven structure of the electronic component includes a bump electrode.~~

~~4. The method for manufacturing an electronic device according to claim 3,~~

~~wherein, when a height of the bump electrode is defined as H [μm] and a thickness of the unevenness-absorbing resin layer is defined as d [μm], H/d is 0.01~~

~~or more and 1 or less.~~

~~5. The method for manufacturing an electronic device according to any one of claims 1 to 4,~~The method for manufacturing an electronic device according to claim 1 or claim2,

wherein the unevenness-absorbing resin layer includes a thermoplastic resin.

~~6~~4. The method for manufacturing an electronic device according to any one of claims 1 to ~~5~~3,

wherein a thickness of the unevenness-absorbing resin layer is 10 μm or more and 1000 μm or less.

~~7. The method for manufacturing an electronic device according to any one of claims 1 to 6,~~5. The method for manufacturing an electronic device according to any one of claims 1 to 4, further comprising:

a first peeling step of peeling the support substrate from the structure by reducing an adhesive force of the adhesive resin layer (B) by applying an external stimulus, after the sealing step.

~~8~~6. The method for manufacturing an electronic device according to claim ~~7~~5, further comprising:

a second peeling step of peeling the adhesive film from the electronic component, after the first peeling step.

~~9~~7. The method for manufacturing an electronic device according to any one of claims 1 to ~~8~~6,

wherein the sealing material is an epoxy resin-based sealing material.

~~10~~8. The method for manufacturing an electronic device according to any one of claims 1 to ~~9~~7,

wherein an adhesive resin forming the adhesive resin layer (A) includes one or two or more selected from a (meth)acrylic-based adhesive resin, a silicone-based

adhesive resin, a urethane-based adhesive resin, an olefin-based adhesive resin, and a styrene-based adhesive resin.